

FINAL PRODUCT CHANGE NOTIFICATION**PCN:** PCN040015**DATE:** November 1, 2004**Subject:** Change of assembly materials for TQFP120 package built at Amkor Korea.**To:****Description of Change:**

Cypress has qualified a new assembly material set for TQFP120 package built at Amkor Korea. The new assembly materials are Sumitomo G700L mold compound and Ablestik 3230. These materials will replace the present assembly materials, which are Sumitomo 7320 mold compound and Ablestik 84-1LMISR4 epoxy.

This change will improve the moisture sensitivity level (MSL) from 5 to 3. There will be no change in fit, form and function of the part.

Benefit of Change: This change will improve the product quality and reliability. Moisture sensitivity level was improved from 5 to 3.

Part Numbers Affected:**Affected Parts: 02**

Affected Part	Description
CYS25G0101DX-ATC	OC-48/STM-16 SONET/SDH Transceiver
CYS25G0101DX-ATI	OC-48/STM-16 SONET/SDH Transceiver

Customer Part Numbers Affected:**Qualification Status:**

As per Cypress specified list of major changes, this change has been qualified through a series of tests identified in Qualification Test Plan (QTP)#034703. The report for closure of this QTP can be found in attachment to this PCN or by going to www.cypress.com, typing the QTP # 034703 in the search window, and clicking

Sample Status:

Samples are available by contacting our local sales office.

Approximate Implementation Date:

The parts will begin shipping in January 2005.

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Anticipated Impact:

Method Of Identification:

This new material set can be identified by the datecode starting 0441.

Response Required:

Your company does not require written approval.

For additional information regarding this change, contact your local sales representative or by E-mail to pcn_adm@cypress.com

Sincerely,

Richard Oshiro
PCN Process Manager